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**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Moden et al.

**Serial No.:** 10/792,222

**Filed:** March 3, 2004

**For:** LOW PROFILE MULTI-IC CHIP  
PACKAGE CONNECTOR

**Confirmation No.:** Unknown

**Examiner:** Unknown

**Group Art Unit:** Unknown

**Attorney Docket No.:** 2269-3389.8US

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

May 13, 2004  
Date

*[Handwritten signature]*  
Signature

Deidra J. Pfeil  
Name (Type/Print)

**PRELIMINARY AMENDMENT**

Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please revise the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.